

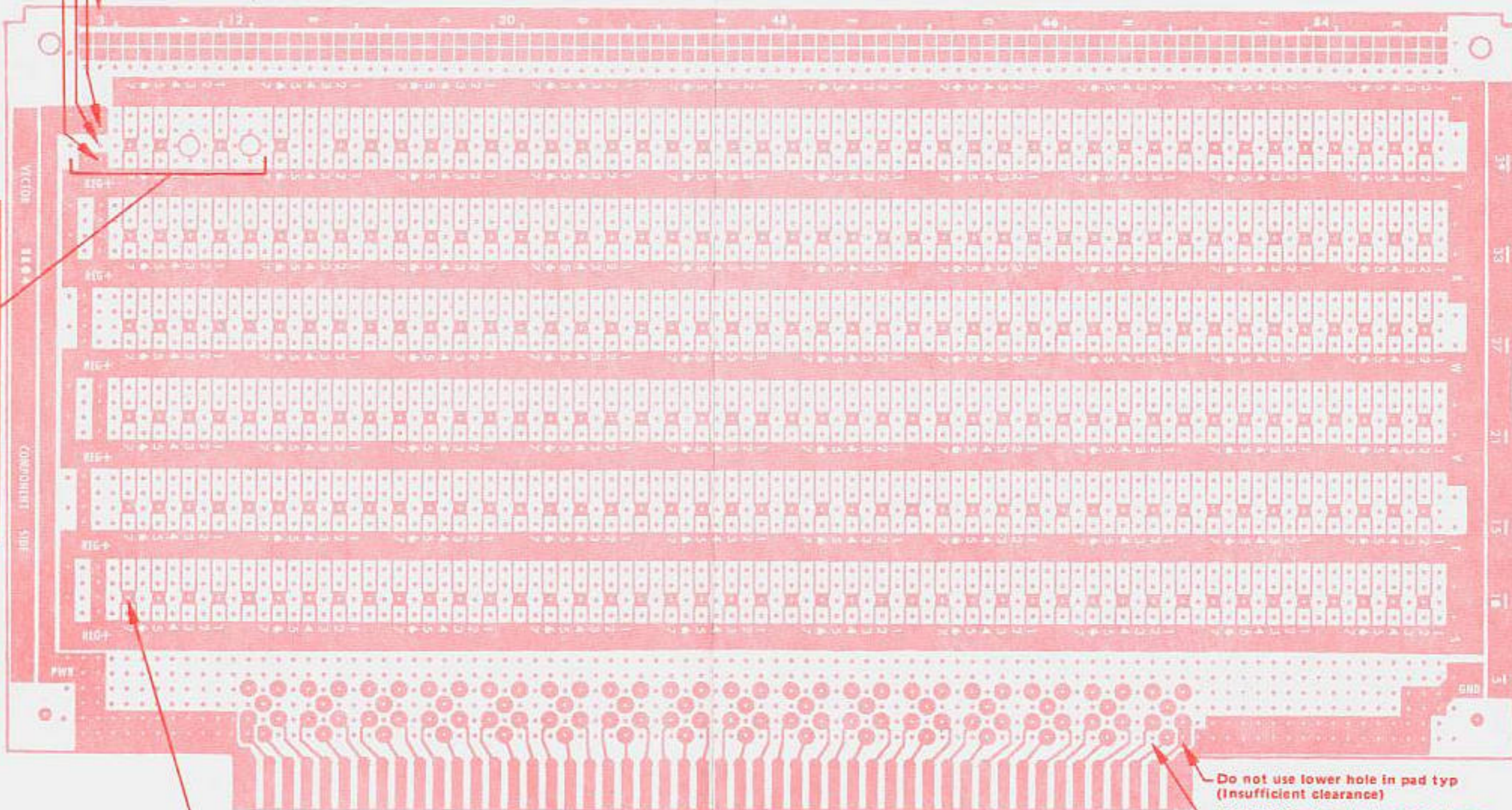
8804 ANY-DIP PLUGBOARD

COMPONENT SIDE LAYOUT PAPER

NOTICE: Where tin coated circuitry exists a small percentage of the holes may have solder blockage. This is **USUALLY** a light "skin" easily penetrated by component leads. In some cases, a soldering iron may be required.

HOLES AT ROW 3
FOR COMMITTED
REGULATOR LEADS
AS FOLLOWS:
POWER IN
GROUND
REGULATOR OUTPUT

THIS AREA MAY BE USED FOR MOUNTING DIPS IN NORMAL MANNER, OR MAY BE USED FOR REGULATOR IN TO-220 CASE, ON HS-1 HEATSINK WITH INSULATING WASHERS AGAINST BOARD ON BOTH SIDES, AT BOTH HOLES.



8. To prevent shorting wrapped wire to etched circuit when wire wrapping, use one or more insulated turns at bottom of Wrap-Pest; also, do not chisel-cut wire against etched circuit as a shorting burr may occur.
 7. Before pressing terminals into board, position (rotate) terminals to maximize the clearance between the widest part of the terminal and the nearest adjacent conductor.
 6. Where tin coated circuitry exists, a small percentage of the holes may have solder blockage. This is usually a light "skin" easily penetrated by component leads. In some cases, a soldering iron may be required.
 5. Intended for use in non-hostile environments up to 200 volts RMS or 300 volts DC.
 4. Bus pads on power plane are offset from those on ground plane.
 3. Floating pads indicate location of connector contact pads on opposite side of boards.
 2. DIPs mount over solid BUS columns.
 1. Zone letters A to K on top border, and S to Z on left border are DIP row & column designator.
- NOTES:**

Do not use lower hole in pad typ
(Insufficient clearance)

CAUTION: In any plug contact area on either side of Plugboard, use only those holes having pads. Holes without pads may have insufficient clearance to adjacent circuitry and using them could cause shorting.

8804 ANY-DIP PLUGBORD WIRING SIDE LAYOUT PAPER

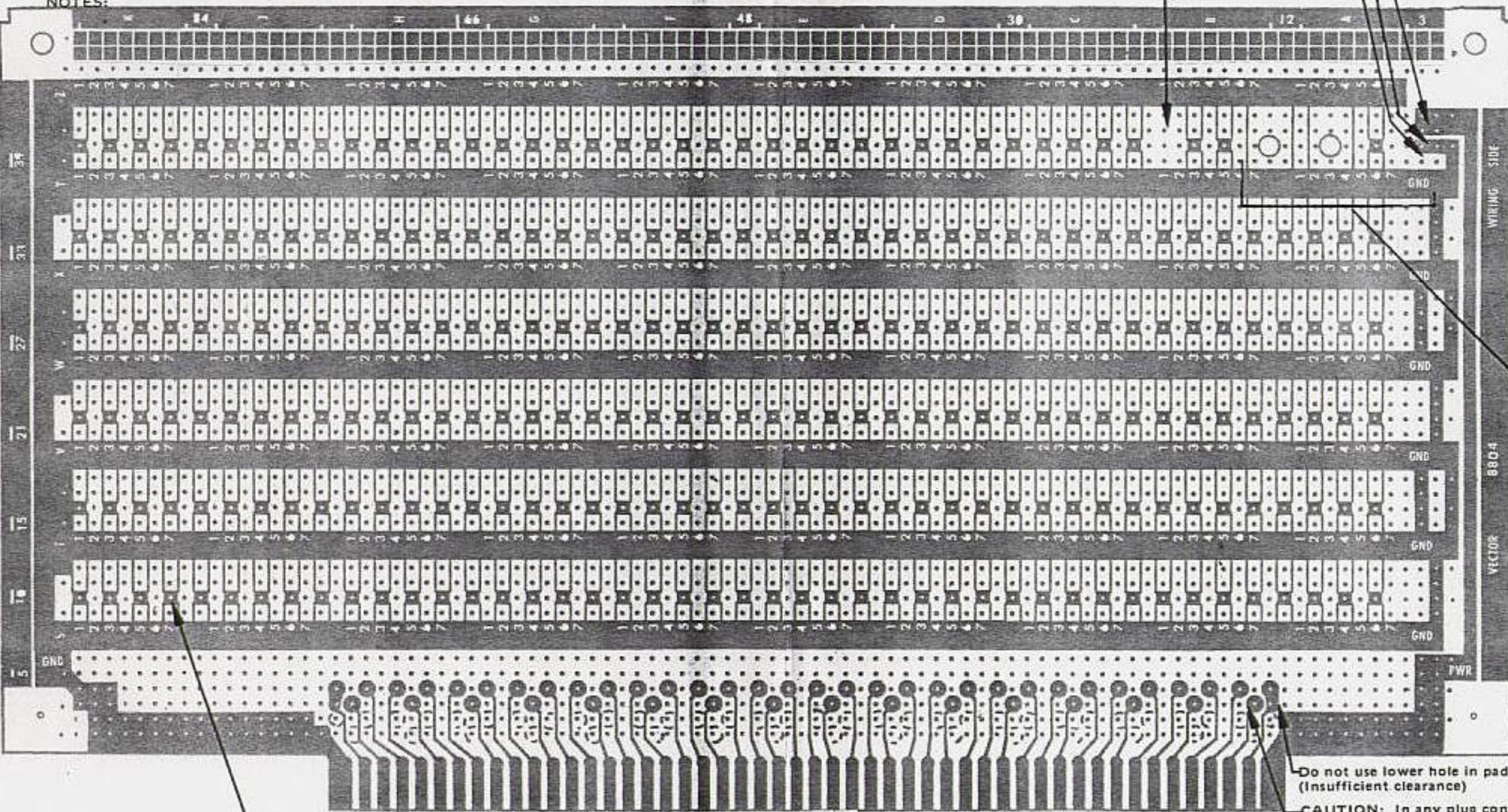
LA19P2

3. TO PREVENT SHORTING WRAPPED WIRE TO ETCHED CIRCUIT WHEN WIRE WRAPPING, USE ONE OR MORE INSULATED TURNS AT BOTTOM OF WRAP POST; ALSO, DO NOT CHISEL-CUT WIRE AGAINST ETCHED CIRCUIT AS A SHORTING BURR MAY OCCUR.
2. BEFORE PRESSING TERMINALS INTO BOARD, POSITION (ROTATE) TERMINALS TO MAXIMIZE THE CLEARANCE BETWEEN THE WIDEST PART OF THE TERMINAL AND THE NEAREST ADJACENT CONDUCTOR.
1. WHERE TIN COATED CIRCUITRY EXISTS, A SMALL PERCENTAGE OF THE HOLES MAY HAVE SOLDER BLOCKAGE. THIS IS USUALLY A LIGHT "SKIN" EASILY PENETRATED BY COMPONENT LEADS. IN SOME CASES A SOLDERING IRON MAY BE REQUIRED.

NOTES:

HOLES AT ROW 20 FOR UNCOMMITTED REGULATOR LEADS

HOLES AT ROW 3 FOR COMMITTED REGULATOR LEADS
REGULATOR OUTPUT
GROUND
POWER IN



THIS AREA MAY BE USED FOR MOUNTING DIPS IN NORMAL MANNER, OR MAY BE USED FOR REGULATOR IN TO-220 CASE, ON HS-1 HEATSINK WITH INSULATING WASHERS AGAINST BOARD ON BOTH SIDES AT BOTH HOLES.

VARIATIONS IN RECEPTACLE CONTACT DESIGNATIONS

- FF AF- 100
- EE AE- 99
- DD AD- 98
- CC AC- 97
- BB AB- 96
- AA - 95
- Z- 94
- Y- 93
- X- 92
- W- 91
- V- 90
- U- 89
- T- 88
- S- 87
- R- 86
- Q- 85
- P- 84
- O- 83
- N- 82
- M- 81
- L- 80
- K- 79
- J- 78
- I- 77
- H- 76
- G- 75
- F- 74
- E- 73
- D- 72
- C- 71
- B- 70
- A- 69
- 68
- 67
- 66
- 65
- 64
- 63
- 62
- 61
- 60
- 59
- 58
- 57
- 56
- 55
- 54
- 53
- 52
- 51

Do not use lower hole in pad typ (Insufficient clearance)

CAUTION: In any plug contact area on either side of Plugbord, use only those holes having pads. Holes without pads may have insufficient clearance to adjacent circuitry and using them could cause shorting.

5. INTENDED FOR USE IN NON-HOSTILE ENVIRONMENTS UP TO 200 VOLTS RMS OR 300 VOLTS DC
 4. BUS PADS ON POWER PLANE ARE OFFSET FROM THOSE ON GROUND PLANE
 3. FLOATING PADS INDICATE LOCATION OF CONNECTOR CONTACT PADS ON OPPOSITE SIDE OF BOARD
 2. DIPS MOUNT OVER SOLID BUS COLUMNS
 1. ZONE LETTERS A TO K ON TOP BORDER, AND S TO Z ON LEFT BORDER ARE DIP ROW & COLUMN DESIGNATORS
- NOTES:

VECTOR D.I.P. PLUGBORD
PATTERN .042" x 0.1" SPACED HOLES
LA19-P2 LAYOUT PAPER

